



Material Composition Sheet

Product: GS4881-ITA
 Package Type: SOIC-8 taped (2500/reel)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		2.54	Al	0.02	0.78	7874
			Si	2.52	99.21	992126
			Sub-total:	2.54	99.99	1000000
Die Attach	84-1 LMISR4	0.14	Aromatic Amine	0.01	7.14	71429
			Epoxy Resin	0.02	14.28	142857
			Silver	0.11	78.57	785714
			Sub-total:	0.14	99.99	1000000
Lead Finish External		0.00		0.00	0.00	0
Lead Finish Internal		0.19	Ag	0.19	100.00	1000000
			Sub-total:	0.19	100.00	1000000
Leadframe	Olin 194FH	24.26	Cu	23.65	97.48	974856
			Fe	0.57	2.34	23495
			P	0.01	0.04	412
			Zn	0.03	0.12	1237
			Sub-total:	24.26	99.98	1000000
Marking Ink		0.00		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME 6300H	46.32	Antimony Trioxide	1.39	3.00	30009
			Brominated Epoxy Resin	0.93	2.00	20078
			Carbon Black	0.14	0.30	3022
			Epoxy Cresol Novolac	7.41	15.99	159974
			Phenol/Novolac resin	2.64	5.69	56995
			Silica Fused	33.81	72.99	729922
			Sub-total:	46.32	99.97	1000000
Wires	SGA3	0.21	Au	0.21	100.00	1000000
			Sub-total:	0.21	100.00	1000000
Total:		73.66				

GENNUM CORPORATION

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